

Agenda

Time	Topic	Speaker
13:00-13:30	Reception	-
13:30-13:45	Keynote	Derek Woo
13:45-14:15	C2000™ F29 MCUs: Enabling edge AI for intelligent condition monitoring and virtual sensing LINK This session explores how TI enables automotive edge artificial intelligence (AI) on C2000™ F29 microcontrollers (MCUs) to enhance value in onboard chargers and traction inverters. F29 MCUs deliver exceptional performance for control and safety applications while leveraging parallel processing capabilities for edge AI. We'll examine intelligent condition monitoring for predictive maintenance and demonstrate how virtual sensing can reduce costs while improving performance.	Andrew
14:15-14:45	Scalable connectivity for every protocol, from smart homes to smart grids LINK This session introduces TI's comprehensive connectivity platform supporting multiple protocols including Bluetooth® Low Energy, Zigbee®, Thread, Matter and Wi-Sun. You will learn how to select the best protocol for applications ranging from consumer electronics to industrial grid infrastructures, accelerating the development of intelligent connected products. The presentation provides practical guidance for implementing connectivity as a core system component rather than just an add-on feature.	Max
14:45-15:15	Preparing for cybersecurity regulations: 3 steps to take now LINK Cybersecurity regulations such as the European Union Cyber Resilience Act will soon affect all businesses shipping products with digital elements to Europe. These rules could disrupt the ability to sell existing products, creating challenges for unprepared manufacturers and opportunities for those who act now. It starts with understanding the impact on currently used components (a list larger than you may expect), and adding infrastructures for security management and vulnerability reporting. In this session, you'll learn what steps to take to help you prepare and gain a competitive advantage as enforcement deadlines approach.	Eddie
15:15-15:30	Break	
15:30-16:00	Replacing ASICs with TI MCUs for advanced analog integration in sensing applications LINK This session covers the advanced analog peripherals in Arm Cortex-M0+ microcontrollers (MCUs) and how they can replace application-specific integrated circuits (ASICs), analog front-end products, or both. We'll demonstrate replacements in applications such as circuit breakers, field transmitters, energy meters and glucose meters, while highlighting ecosystem tools that accelerate design processes.	Eddie

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16:00-16:30	Technology trends and solutions for real-time motor control in appliances and power tools ZLINK The global household appliance market is surging toward 5 billion units by 2029, driven by demand for enhanced performance and features at lower costs. The session introduces technologies for appliances and power tools, including vibration management, high starting torque with speeds >100,000 rpm, low acoustic noise, motor parameter identification, artificial intelligence-powered weight detection and Underwriters Laboratories compliance, helping you innovate and accelerate time to market.	Andrew/Max
16:30-17:00	Ensuring seamless portability across MCU platforms with TI's Zephyr ecosystem ZLINK This session highlights TI's Zephyr ecosystem, emphasizing its advantages for application development and seamless portability across microcontroller (MCU) platforms. We'll present examples enabled by our Zephyr software portfolio, including electronic shelf labels, Bluetooth® Low Energy (LE) Bluetooth Mesh and upcoming support for Bluetooth LE audio. We'll also share how our investments in Zephyr-based testing, using tools such as Twister for automation and validation, ensure reliable solutions across platforms.	Andrew/Max

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